



The 23rd International Conference on Electrical Contacts

6-9 June 2006

Sendai International Center

Announcement



ICEC2006/Sendai

JAPAN

CALL FOR PAPERS (Preliminary)

The 23rd International Conference on Electrical Contacts will be held June 6-9, 2006 at Sendai International Center, Sendai, Japan.

The purpose of the ICEC2006/Sendai is to provide a forum for presenting and discussing the latest development and problems in the field of Electrical Contacts and the related area, and to promote an exchange of science and technical knowledge of specialists from all over the world.

TECHNICAL AREAS AND TOPICS

Basic Phenomena and Fundamentals

Static Contacts

- contact resistance
- fretting corrosion

Make-Break Contacts

- arc phenomena
- arc interruption
- erosion

- welding

Sliding Contacts

- lubrication,
- friction
- wear

Materials

- metals and alloys
- plating
- conductive polymers
- adhesives
- lead free solder

- new materials

Testing and Measurement

- lifetime test
- reliability
- methodology

Evaluation
 modeling
 simulation

Electromechanical and Connection Devices
 switches
 circuit breakers (air and vacuum)
 permanent contacts
 connectors
 relays
 reed switches and reed relays
 micro-motors
 optical connectors and devices

Micro-Electromechanical Devices
 micro-switches
 nano-probes
 micro-welding

Interconnection
 communications
 broadband signal transmission
 degradation effects
 electromagnetic compatibility

Applications
 automotive electrical/electronic components
 communications
 power
 instrumentation
 sensors

New Areas

CONFERENCE LANGUAGE
 English only

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 The Research and Engineering Society for Electromechanical Components and Contact Technology in Japan (RES-ECCT)
 et. al.

ABSTRACT SUBMISSION
 Perspective authors should submit an abstract (maximum 200 words) in English, in word or pdf format to the Program Committee, before November 15, 2005. The abstract must include: title, all authors, affiliation(s), author's postal and electronic addresses, telephone and FAX numbers, and other author's information as paper submission form. Authors will be notified concerning acceptance of abstracts by January 31, 2006.

ADVANCE REGISTRATION FORM
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I am Interested in attending Please Check
 I am interested in presenting paper

Prospective authors who will submit a paper or those who wish to participate the Conference are kindly asked to inform his/her postal and e-mail addresses by sending this registration form to the conference office to receive future communication.

IMPORTANT DATES (Planned)

Final Call for Papers	early summer, 2005
Abstract Deadline	November 15, 2005
Notification of Acceptance	January 31, 2006
Completed Paper Deadline	March 15, 2006
Conference Begins	June 6, 2006

(Tentative list) *Organization Committee:* Tasaku Takagi (Tohoku Bunkagakuken Univ.), *Steering Committee:* Hiroshi Inoue (Akita Univ.), Terutaka Tamai (Hyogo Univ. I.E.), *Executive Committee:* Masasari Taniguchi (Tohoku Bunkagakuken Univ.), *Program Committee:* Koichiro Sawa (Keio Univ.), *Committee of Financial Accounting:* Takoshi Aoki (Tanaka Kikinzoku Kogyo K.K.), *Committee of Public Relations:* Noboru Wakatsuki (Ishinomaki Sensyu Univ.), *Committee of Local Arrangement:* Hideaki Sone (Tohoku Univ.)